

## Features

- 5.5mmx5.0mm RGBW LED
- Full color LED
- Built-in Red / Green / Blue and White quad chip
- High efficiency / high light output
- Pb free and ROHS Compliant product
- SMT compatible package

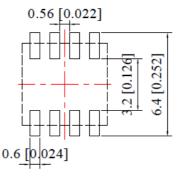
## Applications

- Indication
- Information boards
- Amusement equipment
- Full color application
- General use

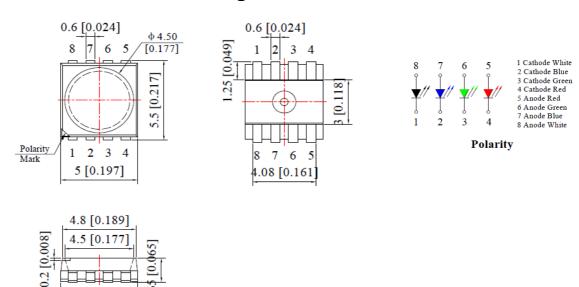
## Description

The IN-P55QDTRGBW is PLCC8 RGBW LED. It is a SMD type LED which can be used in various applications.

## **Recommended Solder Pattern**



#### Figure 1. IN-P55QDTRGBW Solder Pattern



### Package Dimensions in mm

#### Notes.

- 1. All dimensions are in millimeters.
- 2. Tolerance is  $\pm$  0.25 mm unless otherwise noted

5 [0.197]

#### Figure 2. IN-P55QDTRGBW Package Dimensions



## Absolute Maximum Rating at Ta=25°C

Parameter	Symbol	Red	Green	Blue	White	Unit	
Average Forward Current	lF		mA				
Peak Forward Current	I peak	100					
Reverse Voltage	VR	Not designed for reverse operation					
Power Dissipation	PD	52	72	72	108	mW	
Operating Temperature Range	T OPR	-40 ~ 80				°C	
Storage Temperature Range	Т ѕто	-40 ~ 85				°C	
Lead Soldering Condition (Reflow)	T SOL	Below 260°C , Max. 5 seconds					

#### Notes

1. D=0.01s duty 1/10.

#### **ESD** Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

which may be induced by electrostatic discharge (ESD).



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation



# Electrical Characteristics at Ta=25<sup>o</sup>C

	Emission		V <sub>F</sub> (	(V)	λd(nm)	Viewing Angle (°)	Luminous Intensity Iv (mcd)	Luminous Flux Iv (Im)
Product	Color	l⊧(mA)	typ.	max	typ.	<b>20</b> 1/2	typ.	Тур.
	Red	20	2.0	2.6	624	120	500	-
	Green	20	3.2	3.6	525	120	2200	-
IN-P55QDTRGBW	Blue	20	3.2	3.6	470	120	450	-
	White	30	3.2	3.6	CCT=6500K	120	-	10

#### Notes

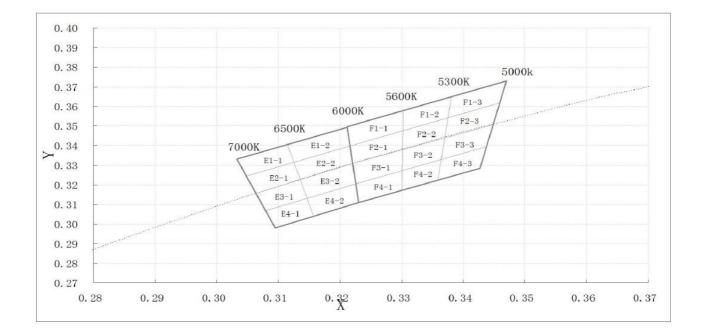
Performance guaranteed only under conditions listed in above tables. Viewing angle(201/2)  $\pm 10^\circ$ 1.

2.



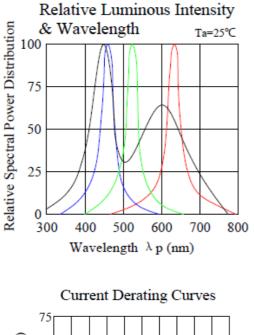
# Chromaticity Bin (for White only)

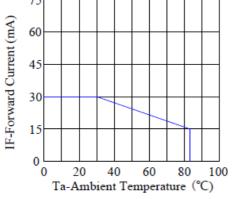
	-		1		1	1		
Bin Code	Left x	Left y	Тор х	Тор у	Right x	Right y	Bottom x	Bottom y
E1-1	0.305	0.324	0.313	0.331	0.312	0.341	0.303	0.333
E2-1	0.306	0.316	0.314	0.323	0.313	0.331	0.305	0.324
E3-1	0.308	0.307	0.315	0.313	0.314	0.323	0.306	0.316
E4-1	0.310	0.298	0.316	0.304	0.315	0.313	0.308	0.307
E1-2	0.313	0.331	0.323	0.340	0.323	0.349	0.312	0.341
E2-2	0.314	0.323	0.323	0.330	0.323	0.340	0.313	0.331
E3-2	0.315	0.313	0.323	0.321	0.323	0.330	0.314	0.323
E4-2	0.316	0.304	0.323	0.311	0.323	0.321	0.315	0.313
F1-1	0.323	0.340	0.330	0.347	0.330	0.357	0.323	0.349
F2-1	0.323	0.330	0.330	0.337	0.330	0.347	0.323	0.340
F3-1	0.323	0.321	0.330	0.327	0.330	0.337	0.323	0.330
F4-1	0.323	0.311	0.330	0.317	0.330	0.327	0.323	0.321
F1-2	0.330	0.347	0.337	0.354	0.338	0.365	0.330	0.357
F2-2	0.330	0.337	0.337	0.343	0.337	0.354	0.330	0.347
F3-2	0.330	0.327	0.337	0.333	0.337	0.343	0.330	0.337
F4-2	0.330	0.317	0.337	0.322	0.337	0.333	0.330	0.327
F1-3	0.337	0.354	0.346	0.362	0.347	0.373	0.338	0.365
F2-3	0.337	0.343	0.345	0.351	0.346	0.362	0.337	0.354
F3-3	0.337	0.333	0.344	0.340	0.345	0.351	0.337	0.343
F4-3	0.337	0.322	0.343	0.328	0.344	0.340	0.337	0.333

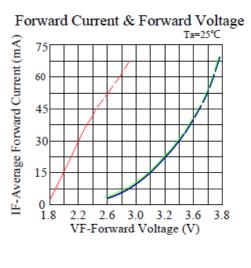


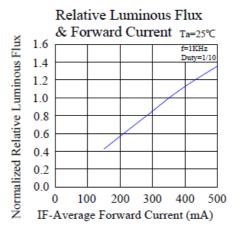


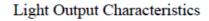
## **Typical Characteristic Curves**

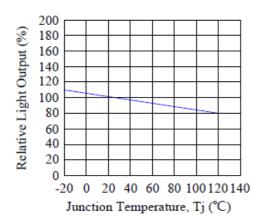






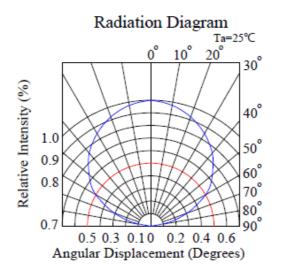








# **Typical Characteristic Curves – Radiation Pattern**

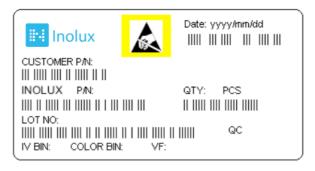


## **Ordering Information**

Product	Emission Color	Test Current I <sub>F</sub> (mA)	Luminous Intensity I <sub>V</sub> (mcd) (Typ.)	Luminous Flux I <sub>∨</sub> (Im) (Typ.)	Forward Voltage V <sub>F</sub> (V) (Typ.)	Orderable Part Number	
	Red	Red		500	-	2.0	
	Green	20	2200	-	3.2		
IN-P55QDTRGBW	Blue	20	450	-	3.2	IN-P55QDTRGBW	
	White	30	-	10	3.2		



## **Label Specifications**



#### **Inolux P/N:**

Ι	Ν	-	Р	5	5	QD	Т			R	G	В	W		-	Х	Х	Х	Х
			Material	Pacl	kage	Variation	Orientation	Current	Lens		Со	lor		Chip Type			istom tamp·		
	ulux ЛD		PLCC - P		.5x5.0	QD = x1.65mm 3 RGBW	T= Top Mount	(Blank) = 20mA	(Blank) = clear		G=52	0nm 25nm 33nm Vhite		(blank) = Standard					

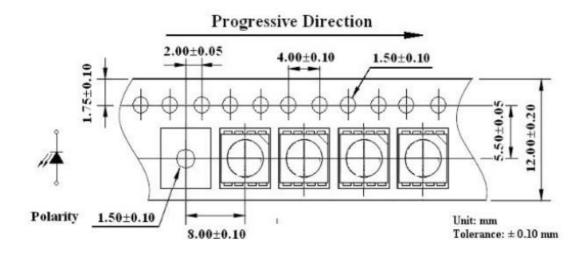
#### Lot No.:

Z	2	0	1	7	01	24	001
Internal		Year (2017,	2019 \	Month	Date	Serial	
Tracker		fear (2017)	, 2018,)		Month	Date	Serial

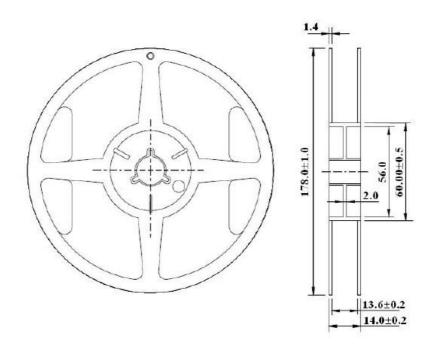


## Packaging Information: 1000pcs Per Reel

## Tape Dimension

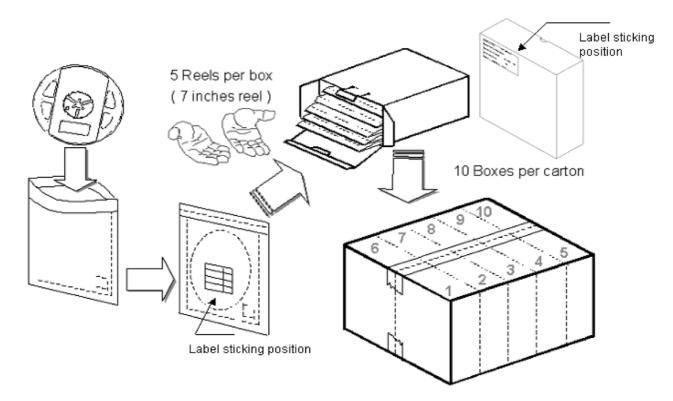


## **Reel Dimensions**





### **Packing Dimension**



5 boxes per carton are available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	1000 pcs
Reel	Per EIA 481-1A specs	Conductive black	
Label	IN standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	IN standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv,  $\lambda_D$  and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

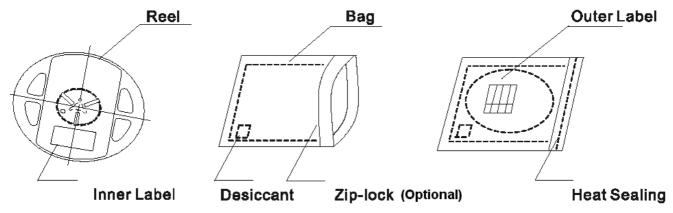


## **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



### **Reflow Soldering**

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Pre-heating 180-200°C 120sec. Max. A\*C/sec. Max. A\*C/sec. Max. A\*C/sec. Max. TIME

Lead-free Solder Profile



### Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

#### Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

#### Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

### **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.



# Reliability

Item	Frequency/ lots/ samples/	Standards	Conditions
Item	failures	Reference	
	For all reliability	J-STD-020	1.) Baking at 85°C for 24hrs
Precondition	monitoring tests according		2.) Moisture storage at 85°C/ 60% R.H. for
	to JEDEC Level 2		168hrs
	1Q/ 1/ 22/ 0	JESD22-B102-B	Accelerated aging 155°C/ 24hrs
Solderability		And CNS-5068	Tinning speed: 2.5+0.5cm/s
			Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s
		CNS-5067	Dipping soldering terminal only
Resistance to			Soldering bath temperature
soldering heat			A: 260+/-5°C; 10+/-1s
Ū			B: 350+/-10°C; 3+/-0.5s
	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs
Operating life test			85°C/ 60%R.H. for 168hrs
			2.) Tamb25°C; IF=20mA; duration 1000hrs
High humidity,	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C
high temperature			Humidity: 85% R.H., IF=5mA
bias			Duration: 1000hrs
High temperature	1Q/ 1/ 20	IN specs.	Tamb: 55°C
bias			IF=20mA
DIAS			Duration: 1000hrs
	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty
Pulse life test			cycle=0.125 (tp=125 µ s,T=1sec)
			Duration 500hrs)
	1Q/ 1/ 76/ 0	JESD-A104-A	A cycle: -40 degree C 15min; +85 degree C
<b>T</b>		IEC 68-2-14, Nb	15min
Temperature			Thermal steady within 5 min
cycle			300 cycles
			2 chamber/ Air-to-air type
High humidity	1Q/ 1/ 40/ 0	CNS-6117	60+3°C
storage test			90+5/-10% R.H. for 500hrs
High temperature	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs
storage test			
Low temperature	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs
storage test			



### **Revision History**

Changes since last revision	Page	Version No.	<b>Revision Date</b>
Initial Release		V1.0	04-22-2019

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